

Singapore HQ:
 Malaysia (North):
 Malaysia (South):
 Thailand:
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SEMICONDUCTOR








PRINCIPAL	COMPANY	COUNTRY	PRODUCT DESCRIPTION
EQUIPMENT			
	FSM	USA	Wafer Film Stress/Raman Spectroscopy/Film Thickness Measurement
			Low-k/Cu Material Stress Hysteresis/Thermal Desorption Measurement
			Sheet Resistivity/Leakage for Ultra-Shallow Junction Measurement
			Thin Wafer Thickness/Roughness/Warp/Bump Height Measurement
			3-Point/Notch Die Strength Tester (after dicing)
			4-Point Bend Environmental Low-k Adhesion Tester
			Surface 3D Video Microscope and Surface Profiler
			Step, MEM Measurement
			Wafer Defect Inspection system
	Nanophotonics	Germany	Auto & Manual Defect Inspection system for Particle, Area defect
			Auto & Manual Defect Inspection system for edge-to-edge / orientated / handling scratches
			Front, Back, Edge defect inspection system
	Thermo Fisher Scientific	USA	Microbeam XRF Coating Thickness/Composition Measurement System
			Wafer Thin Film Metal Thickness Measurement System
	Matrix Metrologies	USA	XRF Substrate/Leadframe Plating Thickness Measuring System
			Handheld XRF Plating Thickness/RoHS Analysis System
	ASC International	USA	Semi-Auto/Offline Solder Paste/Bump 3D Measurement System
			Semi-Auto/Offline Adhesive 3D Measurement System
SOFTEX	*SOFTEX	Japan	Solder Joint X-Ray Inspection System
			Semiconductor X-Ray Inspection System
	*ARCS	Taiwan	Manual/Auto Non contact Coordinate Measuring Machine
			X-Y-Z dimension measurement
	JDI & Kunoh	Japan	system, Coordinate Measuring Machine,
			Spin Coater/Spin Etcher//Developer/Spin Cleaner
			Mask Aligner/Mask Cleaner/Plasma Cleaner
			CVD System/Vacuum Anodic Bonder

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SEMICONDUCTOR

PRINCIPAL	COMPANY	COUNTRY	PRODUCT DESCRIPTION
EQUIPMENT / MATERIAL - PRODUCTION			
	G&N	Germany	Wafer Grinding, Thinning & Polishing System
			Ultra-Thin Wafer Thinning System
			Wafer Edge Grinding System
	MATECH	USA	Wafer Thinning by Wet Etching (down to 10 um)
			Silicon Nitride/Silicon Oxide Film Thinning
			Wafer Pattern Etching
	Advanced Engineering	Canada / Israel	Vacuum Wafer Mounter
			Wafer UV Curing System
			Wafer Cleaning System
	Mirachem	USA	Dicing/Grinding Coolant/Cleaner/Lubricant Solution (Material)
			Photonics Cleaning Solution (Material)
	Dynavest heat-resistant Complex stone	Singapore	Heat resistance compound material for reflow process
			Complex stone uses resin that provide the resistance to chemical use in flux & reduce solder dust
			PCBA fixture (tooling) can be manufactured due to its characteristic
	Silicon Media	Taiwan	Dicing Blade consumable parts
	Zymet	USA	BGA/CSP/Flip Chip Underfill (Material)
			ACP/NCP/Epoxy Adhesive and Encapsulant (Material)
			UV-Cured Adhesive and Encapsulant (Material)
****SPINDLE REPAIR SERVICES FOR AIR & BALL BEARING SPINDLES			

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PHOTOVOLTAIC

PRINCIPAL	COMPANY	COUNTRY	PRODUCT DESCRIPTION
EQUIPMENT & MATERIAL: PRODUCTION			
	LOG-O-Matic	Germany	Diamond Wire Band Saw for Ingot to Solar Brick
			Silicon IR Inspection System
			Band Saw for Top cut of Solar Brick
	G&N	Germany	Surface Grinding & Chamfering System for Poly & Mono Crystalline
			Solar brick
			Grinding of Solar Wafer
	Secon	Germany	Dry Plasma Texturing to improve efficiency of solar cell
			Remove surface damage
	CHEMCUT	USA	Cleaning, Developing, Etching, Drying Line
	Meier	Germany	Vacuum Laminator of Solar Module
			Multi-Stack Vacuum Laminator
EQUIPMENT: METROLOGY, TEST & INSPECTION			
	FSM	USA	Non-Contact Junction photo-Voltage, Sheet Resistance
			Carrier Diffusion Length & Leakage Current Measurement System
			Wafer Film Stress/Raman Spectroscopy/Film Thickness Measurement
			Sheet Resistivity/Leakage for Ultra-Shallow Junction Measurement
			Wafer Thickness/Roughness/Warp Measurement
	FSM	USA	Surface 3D Video Microscope and Surface Profiler
			Step, MEM Measurement
	Solar Metrology	USA	CIGS, CdTe Thickness & Composition
			Complex Alloy Deposition Measurement System
			Handheld XRF Plating Thickness/ROHS Analysis System
	Thermo Fisher Scientific	USA	Microbeam XRF Coating Thickness & Composition
			Wafer Thin Film Metal Thickness Measurement System
	JDI	Japan	Solar Cell Tester measure I-V Characterization
			Inspection and Measurement Microscope

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